Gap Pad® VO Ultra Soft

Ultra Conformable, Thermally Conductive Material for Filling Air Gaps

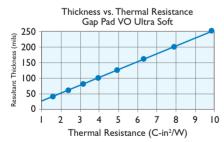
Features and Benefits

- Thermal conductivity: I.0 W/m-K
- Highly conformable, low hardness
- "Gel-like" modulus
- Designed for low-stress applications
- Puncture, shear and tear resistant



Gap Pad VO Ultra Soft is recommended for applications that require a minimum amount of pressure on components. The viscoelastic nature of the material also gives excellent low-stress vibration dampening and shock absorbing characteristics. Gap Pad VO Ultra Soft is an electrically isolating material, which allows its use in applications requiring isolation between heat sinks and high-voltage, bare-leaded devices.

Note: Resultant thickness is defined as the final gap thickness of the application.



Mauve/Pink Sil-Pad 0.020 to 0.250	Mauve/Pink Sil-Pad 0.508 to 6.350	Visual —
0.020 to 0.250	0.508 to 6.350	
	0.000 10 0.000	ASTM D374
I	1	
1.6	1.6	ASTM D792
1.0	1.0	ASTM E1269
5	5	ASTM D2240
8	55	ASTM D575
-76 to 392	-60 to 200	_
>6000	>6000	ASTM D149
5.5	5.5	ASTM D150
1011	10"	ASTM D257
V-O	V-O	U.L. 94
1.0	1.0	ASTM D5470
	1.0 5 8 -76 to 392 >6000 5.5 10" V-O	1.0

Typical Applications Include:

- Telecommunications
- Computer and peripherals
- Power conversion
- Between heat-generating semiconductors or magnetic components and a heat sink
- Area where heat needs to be transferred to a frame, chassis, or other type of heat spreader

Configurations Available:

• Sheet form and die-cut parts

Building a Part Number

GPVOUS - 0.100 - AC - 0816 NΑ Δ NA = Selected standard option. If not selecting a standard Section Section Section Section option, insert company name, drawing number, and 0816 = Standard sheet size 8" x 16", or 00 = custom configuration AC = Adhesive, one side 00 = No adhesive Standard thicknesses available: 0.020", 0.040", 0.060", 0.080", 0.100", 0.125", 0.160", 0.200", 0.250" GPVOUS = Gap Pad VO Ultra Soft Material

Standard Options

Note: To build a part number, visit our website at www.bergquistcompany.com.

Gap Pad®: U.S. Patent 5,679,457 and others.



²⁾ Young's Modulus, calculated using 0.01 in/min. step rate of strain with a sample size of 0.79 inch². For more information on Gap Pad modulus, refer to Bergquist Application Note #116.